

The Chips Venture Forum

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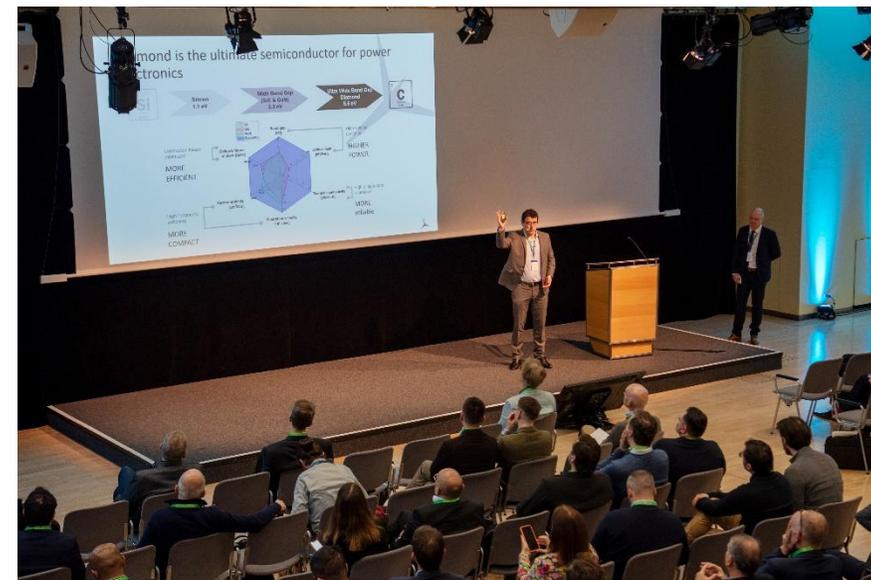
NETWORK OF COMPETENCE CENTERS, IN PARTNERSHIP WITH EIC –ACCELERATOR AND DG CONNECT



IN PRESENCE OF DEEP TECH VENTURE CAPITAL INVESTORS, CORPORATE VENTURES, CORPORATES



FIRST EDITION IN MÜNICH – SEMICON EUROPE 18TH OF NOVEMBER, 2025



A partnership between:



European Innovation Council



aCCcess has received funding from the European Union's Digital Europe Chips JU under Grant Agreement No 101217840.





150+
participants

18 start-ups
selected to pitch



Funded by the
European Union

aCCcess has received funding from the European Union under the European Chips JU under Grant Agreement



100+ One on One Meetings



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VERTICAL COMPUTE - Winner SPINNnCLOUD – Coup de coeur FARADAIC – Coup de coeur



More than 50M€ raised or under negotiation

- 5 companies raised funds
- 5 companies have on-going discussions
- Deal sizes from early stage to series B
 - 2 deals > 10M€
 - 4 deals from 1 to 5M€
 - 4 deals > 1M€

What they say about the CVF

“The whole program was great”

Sarah Luppino M Ventures

*The interest of the Chips Venture Forum for my organization lies in
“Formation of ecosystem Building a pipeline for our investments”*

Hemut Gassel Silian Partners

*“It's great to have investors together, which have a real focus
on deep tech. This makes discussions efficient and to the
point.”*

Steve Stoffels Aluvia Photonics

*The interest of the Chips Venture Forum for my organization is
to “screen new potentials of start-ups, develop a network
focused on innovation and Europe sovereignty”*

Antoine Amade Entegris



70+ Confirmed Jury Members & Investors

- **Alain Le Loux** – CEO, Cottonwood Technology Fund
- **Bedwyr Humphreys** – Chief Development Officer, Lam Capital
- **Pieter Klinkert** – Partner & Co-Founder, Photon Ventures
- **David Hurley** – Senior Venture Partner, TEL Venture Capital
- **Christian Claussen** – General Partner, Ventech
- **Giovanni Bologna** – Portfolio Manager, Santander
- **Alessandra Scotti** – Institutional Relations & Scouting, LIFTT
- **Novica Mrdovic-Vianello** – General Partner, Mountain X
- **Paul Murray** – Partner, Atlantic Bridge
- **Giorgia Mila** – Deal Flow Manager, Obloo
- **Olivier Rits** – VC Investment Manager, KBC Focus Fund
- **Mathieu Costes** – Partner, Airbus
- **Bert Gyselincks** – Partner, IMEC xband
- **Hind Beaujon** - Senior Vice President Global Sales, Suss Microtec
- **Christian Reitberger** – Partner, Matterwave Ventures
- **Stéphane Mutz** – Partner, Deeptech XL
- **Alberto PINTADO** - Head of Indra Ventures
- **Gijs VAN DER HULST** – Founding Partner, Positron Ventures
- **Itaru Shiraishi** - Head of Global Business Development, EE investments
- **Lars Boehnisch** – Investment Manager, Evonik Venture Capital
- **Sarah Benhamou** – Principal, BGV
- **Maarten ter Keurst** – Managing Partner, Natural Ventures
- **Georg Stricker** – Tech Partner and Managing Director, Signature Ventures
- **Klaus Kummermehr** – Partner, SNGLR
- **François Tison** – General Partner, 360 Capital Partners
- **Gianluca Dettori** – Chairman General Partner, Primo Capital
- **Remy de Tonnac** – Senior Partner, ETF Partners
- **Celine Schulze** – Co-Founder & CEO, Narwhale Ventures
- **Cecile Real** – CEO, Medevice Capital
- **Heribert UHL** - Senior Investment Director, Robert Bosch Venture Capital
- **José Marino García** – Executive Director for Capitalization, SETT
- **Thomas Belaid** – Investment Manager, Safran Corporate Ventures
- **Jorg Nowack** – EMEA Growth Strategy & Open Innovation, Hitachi High-Tech
- **Ulrich KRUSE** - Investment Manager, TRUMPF Venture
- **David DANA** – Head of VC Investments, Expansion Ventures
- **Wojtek Smolinski** - Managing Partner, Vigo Ventures
- **Olivier Tonneau** – Partner, Quantonation
- **Sarah Luppino** – Principal Technology Investments, M Ventures
- **Boris DORIN** – Partner, First Imagine
- **Antoine AMADE** – Regional director emea sales, Entegris
- **Hans Brower** – Founder, Riverside Investments
- ...

Chips Venture Forum 2026



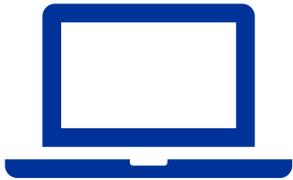
aCCcess in partnership with EIC & DG-CNCT

1st Eligibility requirement:

- Startup affiliated with a European Competence Center (CCC)
- Or EIC supported companies

A competition in 2 phases: 2 face to face events

Selection



Online



CVF at INPHO Venture
Summit Bordeaux

Final



Back to Back to Semicon
Munich



1. Selection in Bordeaux : The Chips Venture Forum selection meeting will be embedded in the INPHO Venture Summit



ABOUT INPHO



“What’s next to invest in Deeptech”

Recognised biennial summit :

A Meeting Point for Deeptech Investors, including the Semiconductor Sector

1 000

GUESTS

hand-picked decision-makers
interested in transformative
technology investment

150

SPEAKERS

World-known and
forward-thinking

24

COUNTRIES

from Europe, USA,
Japan, and more.

+1B€

CAPITAL RAISED

EDITORIAL COMMITTEE



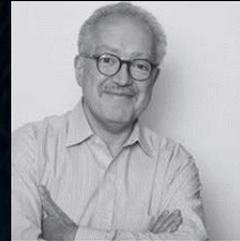
GEORGE UGRAS
Chairman - Managing
Director at AV8 Ventures



HERVE FLOCH
General Manager at
ALPHA-RLH



GERALDINE ANDRIEUX
CEO at BLUMORPHO



ERIC BENHAMOU
Founder at Benhamou
Gloal Ventures



FRANCOIS TISON
General Partner at 360
Capital Partner



AYMERIK RENARD
General Partner at HCVC



MATHIEU COSTES
Partner at Airbus
Ventures



CHRISTIAN REITBERGER
Partner at Matterwave
Ventures



HIND BEAUJON
Chief Sales Officer at
Pfeiffer Vacuum
Technology



NICOLAS LETERRIER
Semiconductor
Sustainability Business
Leader At Schneider
Electric



OLIVIER TONNEAU
Founder and Partner at
Quantonation



GIANLUCA DETTORI
Chairman, General
Partner at Primo Capital



CHRISTIAN CLAUSSEN
General Partner at
Ventech



GUUS FRERICKS
Founder & Managing
Partner at DeepTechXL



GIOVANNI BOLOGNA
Portfolio Manager at
Santander Asset
Management

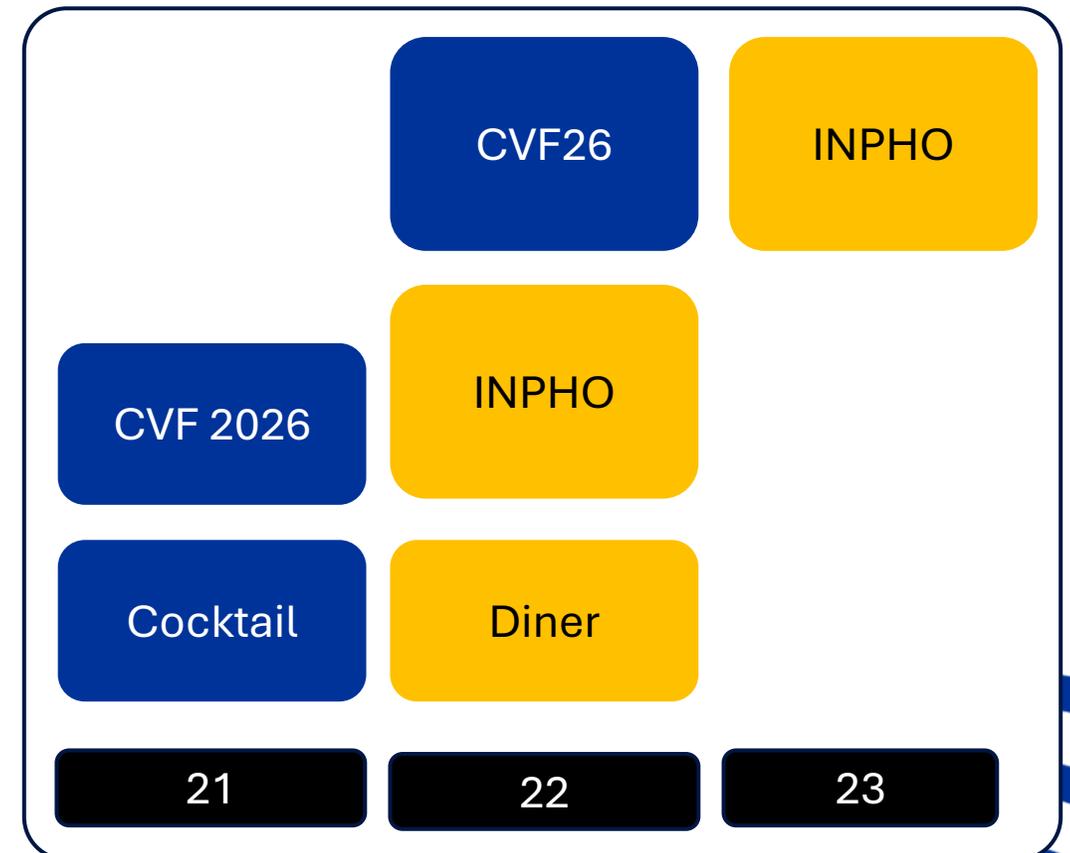


The Chips Venture Forum: Selection

21 & 22 October 2026

The Chips Venture Forum 2026 is leveraging INPHO Venture Summit.

- Access to the INPHO investor network: participants to the Chips Venture Forum **will have the full access to the INPHO Venture Summit**
- More time with investors
- Stronger engagement with semiconductor end-users
- Dedicated 1:1 meeting spaces
- Broader exposure to cross-cutting strategic topics





Location : Palais de la Bourse



 Palais de la Bourse,
17 place de la Bourse, Bordeaux



One on One



Networking



Pitching session



Insights



Funded by the
European Union

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2. CVF26 Final in Semicon - Munich



The Chips Venture Forum Final

11-13 November 2026



Location : Messe Munchen



Nov 10–13, 2026 | MESSE MÜNCHEN | Co-located with electronica



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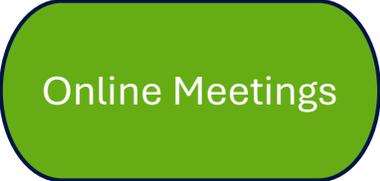
The Process



17/03

12/05

CC are communicating about the Chips Venture Forum to their startups



03/06

12/06

Online Meetings

CC Stage Pitch Selection



Pitch Preparation



21/10- 22/10

inpho



Chips Venture Forum Selection : Bordeaux

- CC startups pitching sessions
- One to one meetings focused on fundraising

10/11- 13/11
Date TBD



Chips Venture Forum Finale : Semicon - Munich

- Semiconductor Startups pitching sessions
- Networking: investors, semiconductor corporates, and system integrators

Selection criteria – CCC Startups

Technology scope is unchanged

Startups must operate in at least one of the following domains:

- Mainstream Silicon Technologies,
- EDA & Design Automation,
- Packaging & Assembly,
- Test & Instrumentation Equipment,
- Materials & Substrates,
- Process Equipment & Manufacturing Tools,
- Power Electronics,
- MEMS & Sensors,
- RF & mmWave,
- AI/ML Hardware,
- Silicon Photonics,
- Quantum Technologies.





Request the application link from your Competence Center



aCCcess

Find your CCC on:

<https://www.access.eu/>

Or send an email to:

contact@access.eu



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PROJECT PARTNERS